

Stripper L 60

Stripper L 60 is a chemical operating two-step-spray-process for the removal of tin, tin-lead and lead deposits from copper. This process is preferably applied in the PCB production for stripping of metal resists if PCB's are manufactured in the copper only technology. In the first operating step, the metal resists tin, tin-lead and lead are removed by the support of Stripper L 60. Copper-tin diffusion layers, which remain after tin- or lead-tin coatings have been stripped off will be removed with Copper Activation S 40 in the subsequent operating step. At the same time this process guarantees optimum adhesion of the solder mask.

The process is free from complexing agents, fluorides, nitric acid and hydrogen peroxide, and so it can be disposed without special effort. Analytical control of the process is not required.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

